

extension, and credit any overpayment, to Deposit Account 06-1205.

IN THE CLAIMS

Please cancel Claims 1 and 15 without prejudice or disclaimer of subject matter.

Please amend Claims 14 and 16-19 to read as follows, and add Claims 26-31 to read as follows (a version of the amended claims, marked to show the changes thereto, is appended):

B' Sub 017 14. (Amended) A photovoltaic element encapsulated with an encapsulant resin, the encapsulant resin comprising an ultraviolet absorbing agent dissolved therein, wherein the dissolved ultraviolet absorbing agent has a concentration gradient in the direction of thickness of the encapsulant resin.

B2 16. (Amended) The photovoltaic element according to Claim 14, wherein the additive is at least one selected from a silane coupling agent and an ultraviolet absorbing agent.

17. (Amended) The photovoltaic element according to Claim 14, wherein the concentration of the additive is higher at a location near the semiconductor element but lower at a location remote from the semiconductor element.

B2  
end

18. (Amended) The photovoltaic element according to Claim 14,  
wherein the concentration of the additive is lower at a location near the semiconductor  
element but higher at a location remote from the semiconductor element.

19. (Amended) The photovoltaic element according to Claim 14,  
wherein the additive is an adhesive.

B3  
5th

20. (New) The photovoltaic element according to Claim 14, wherein the  
concentration of the ultraviolet absorbing agent is higher at a location near a light incident  
surface of the encapsulant resin.

sub C27

27. (New) The photovoltaic element according to Claim 14 or 26, further  
comprising a silane coupling agent dissolved in the encapsulant resin.

sub E7

28. (New) The photovoltaic element according to Claim 27, wherein the  
concentration of the silane coupling agent is higher at a location near the photovoltaic  
element.

29. (New) The photovoltaic element according to Claim 27, further  
comprising a surface member provided on a surface of the encapsulant resin.